



SOT629-1

plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 4 x 4 x 0.85 mm

21 December 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN16
Package type industry code	HVQFN16
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-10-2002
Manufacturer package code	SOT629

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
seated height	-	0.85	1	mm
package height	-	0.85	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

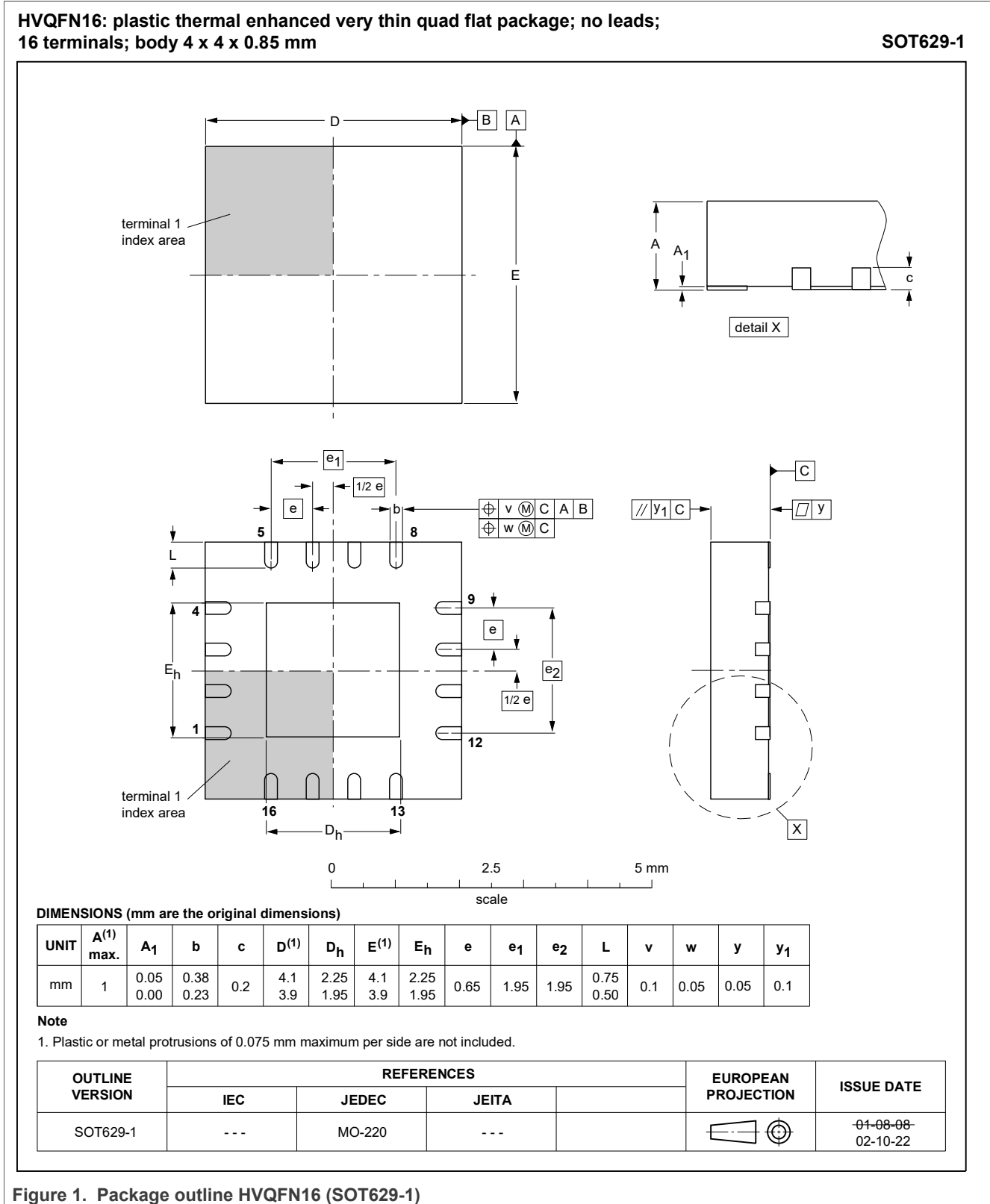


Figure 1. Package outline HVQFN16 (SOT629-1)

plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 4 x 4 x 0.85 mm

3 Soldering

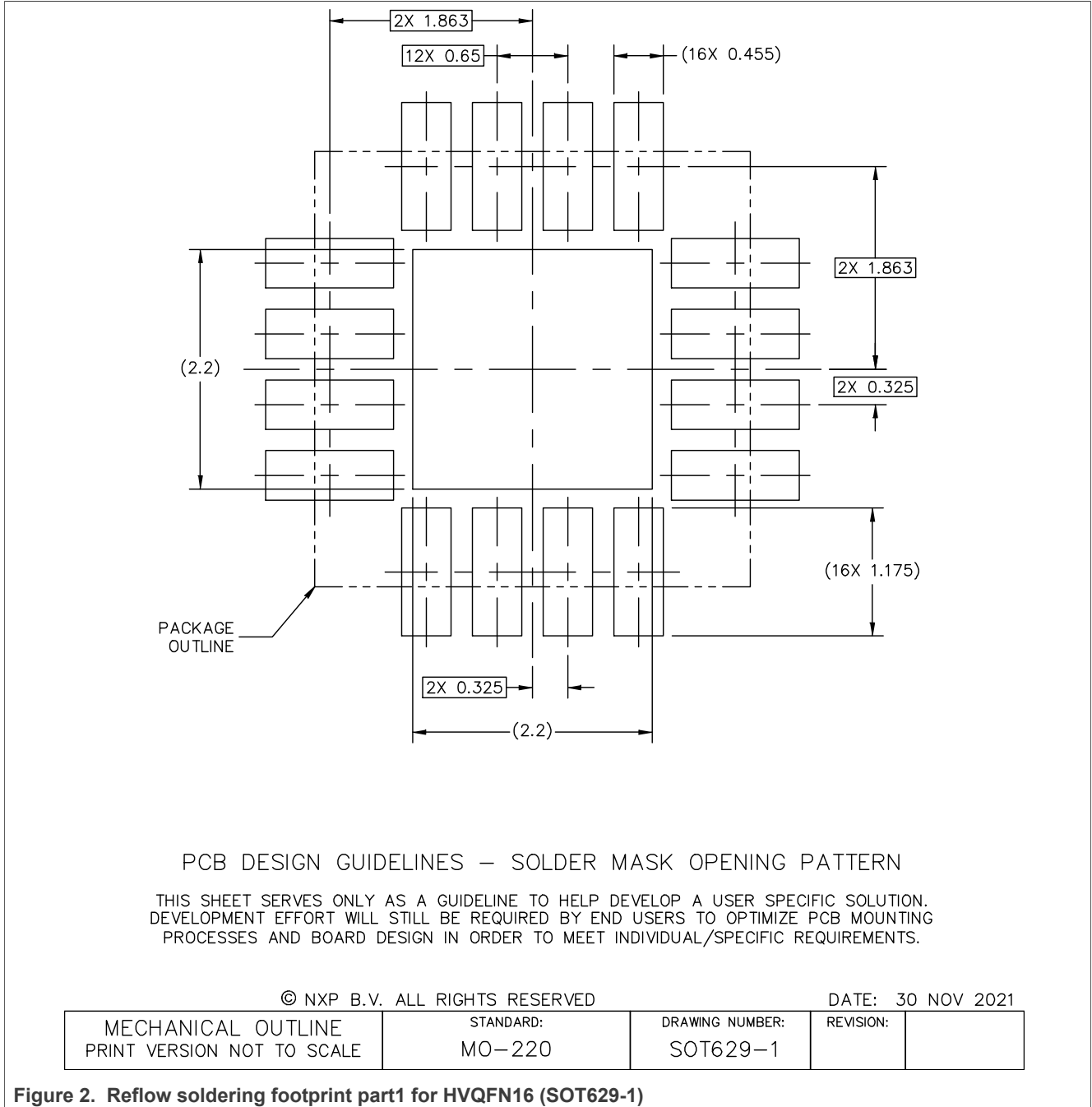
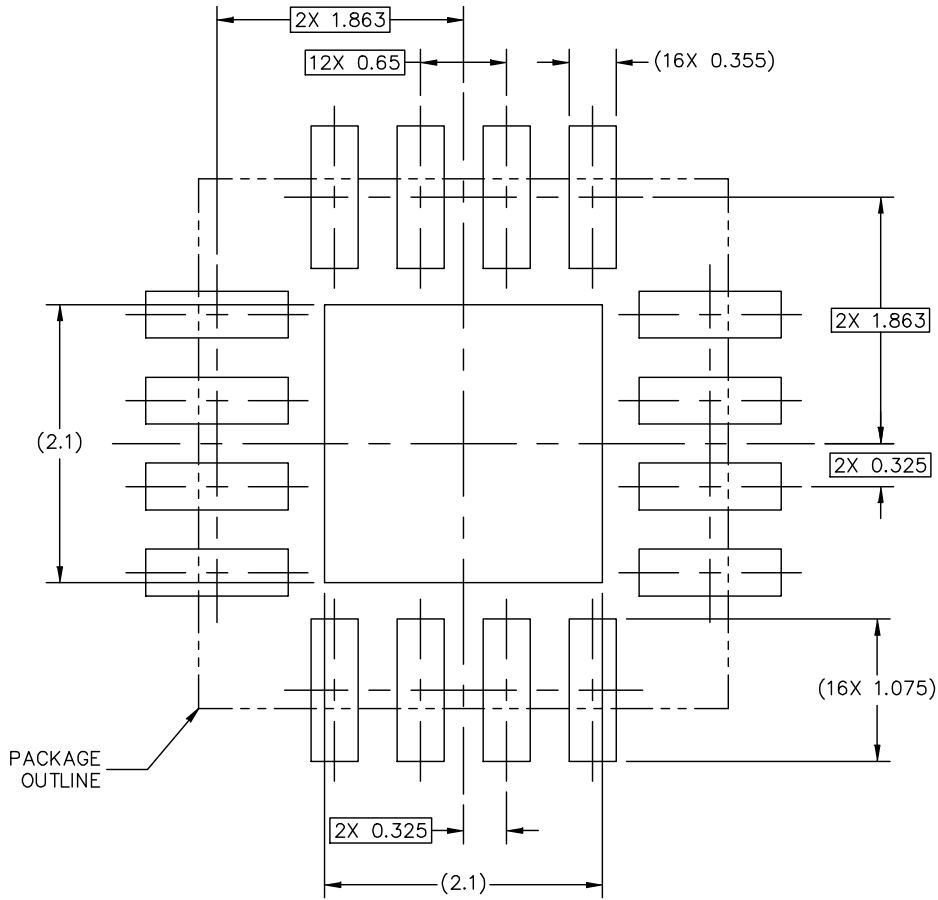


Figure 2. Reflow soldering footprint part1 for HVQFN16 (SOT629-1)

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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DATE: 30 NOV 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: SOT629-1	REVISION:
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Figure 3. Reflow soldering footprint part2 for HVQFN16 (SOT629-1)

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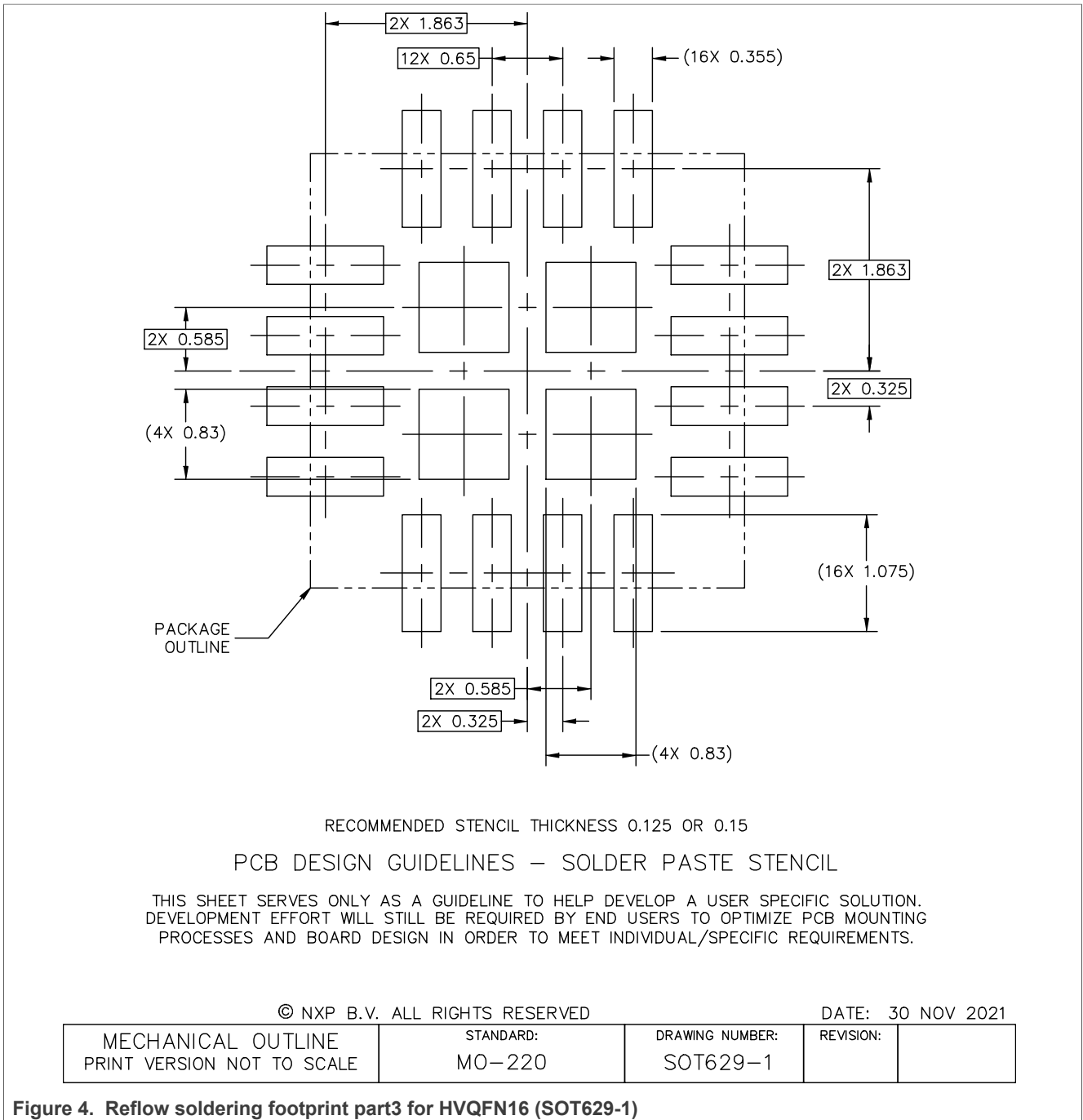


Figure 4. Reflow soldering footprint part3 for HVQFN16 (SOT629-1)

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4 Legal information

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